

ESD5451N

1-Line, Bi-directional, Transient Voltage Suppressors

Descriptions

The ESD5451N is a bi-directional TVS (Transient Voltage Suppressor). It is specifically designed to protect sensitive electronic components which are connected to low speed data lines and control lines from over-stress caused by ESD (Electrostatic Discharge), EFT (Electrical Fast Transients) and Lightning.

The ESD5451N may be used to provide ESD protection up to $\pm 30 \text{kV}$ (contact and air discharge) according to IEC61000-4-2, and withstand peak pulse current up to 8A (8/20µs) according to IEC61000-4-5.

The ESD5451N is available in DFN1006-2L package. Standard products are Pb-free and Halogen-free.

Features

- Reverse stand-off voltage: ±5V Max
- Transient protection for each line according to IEC61000-4-2 (ESD): ±30kV (contact and air discharge) IEC61000-4-4 (EFT): 40A (5/50ns) IEC61000-4-5 (surge): 8A (8/20µs)
- Capacitance: C_J = 17.5pF typ.
- Low leakage current: I_R < 1nA typ.
- Low clamping voltage: V_{CL} = 9V typ. @ I_{PP} = 16A (TLP)
- Solid-state silicon technology

Applications

- Cellular handsets
- Tablets
- Laptops
- Other portable devices
- Network communication devices

http//:www.sh-willsemi.com



DFN1006-2L (Bottom View)



Circuit diagram



2 = Device code

* = Month code (A~Z)

Marking (Top View)

Order information

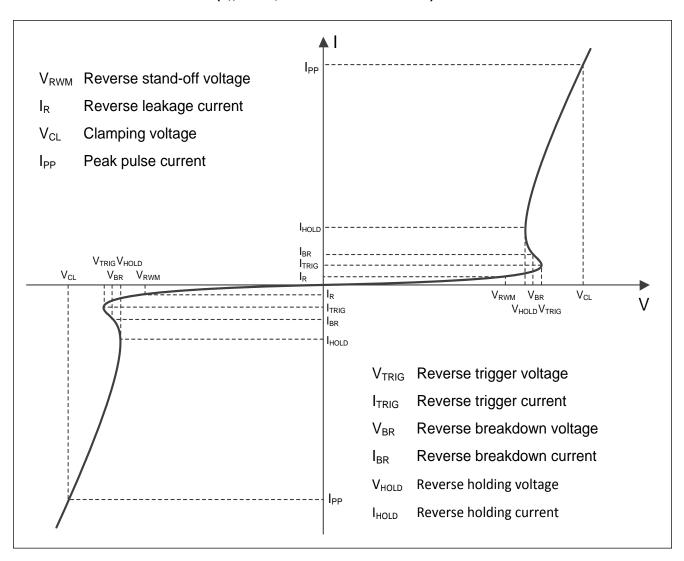
Device	Package	Shipping		
ESD5451N-2/TR	DFN1006-2L	10000/Tape&Reel		



Absolute maximum ratings

Parameter	Symbol	Rating	Unit	
Peak pulse power (t _p = 8/20µs)	P_{pk}	80	W	
Peak pulse current (t _p = 8/20µs)	I _{PP}	8	А	
ESD according to IEC61000-4-2 air discharge	V	±30	kV	
ESD according to IEC61000-4-2 contact discharge	V_{ESD}	±30		
Operation junction temperature	TJ	125	°C	
Lead temperature	TL	260	°C	
Storage temperature	T _{STG}	-55~150	°C	

Electrical characteristics (T_A=25 °C, unless otherwise noted)



Definitions of electrical characteristics



Electrical characteristics (T_A=25 °C, unless otherwise noted)

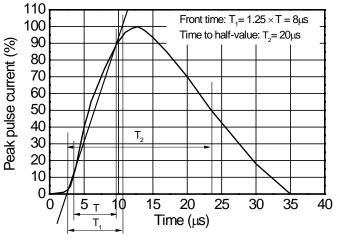
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				±5	V
Reverse leakage current	I _R	V _{RWM} = 5V		<1	100	nA
Reverse breakdown voltage	V_{BR}	I _{BR} = 1mA	5.1			V
Reverse holding voltage	V _{HOLD}	I _{HOLD} = 50mA	5.1			V
Clamping voltage 1)	V _{CL}	$I_{PP} = 16A, t_p = 100ns$		9		V
Clamping voltage 2)	V _{CL}	V _{ESD} = 8kV		9		V
		$I_{PP} = 1A, t_p = 8/20 \mu s$			6.5	V
Clamping voltage 3)	V _{CL}	$I_{PP} = 5A$, $t_p = 8/20 \mu s$			8.5	V
		$I_{PP} = 8A, t_p = 8/20 \mu s$			10	V
Dynamic resistance 1)	R_{DYN}			0.20		Ω
lunction consoitance	CJ	$V_R = 0V$, $f = 1MHz$		17.5	22	pF
Junction capacitance		V _R = 5V, f = 1MHz		11.5	16	pF

Notes:

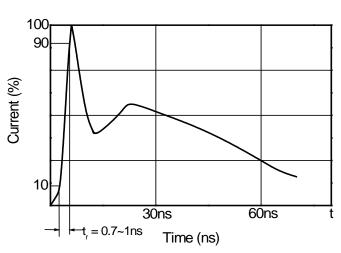
- 1) TLP parameter: $Z_0 = 50\Omega$, $t_p = 100$ ns, $t_r = 2$ ns, averaging window from 60ns to 80ns. $R_{\rm DYN}$ is calculated from 4A to 16A
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.



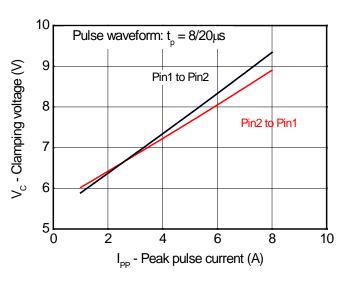
Typical characteristics (T_A=25°C, unless otherwise noted)



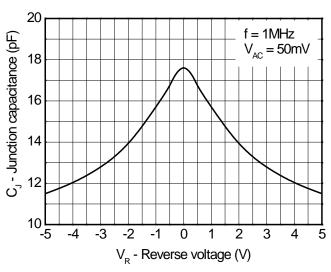
8/20µs waveform per IEC61000-4-5



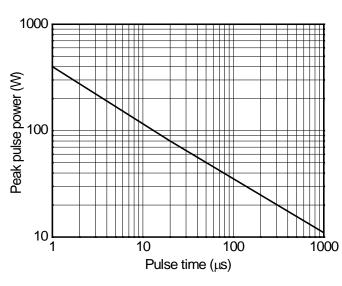
Contact discharge current waveform per IEC61000-4-2



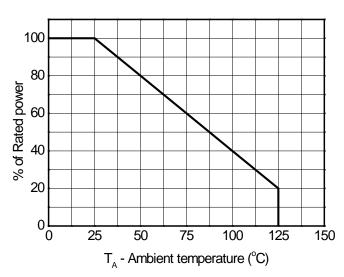
Clamping voltage vs. Peak pulse current



Capacitance vs. Reveres voltage



Non-repetitive peak pulse power vs. Pulse time

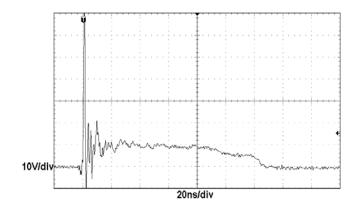


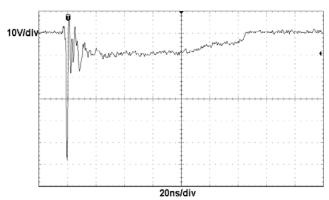
Power derating vs. Ambient temperature

4



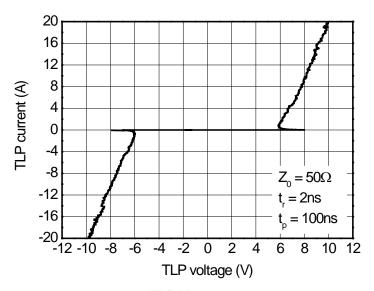
Typical characteristics (T_A=25°C, unless otherwise noted)





ESD clamping (+8kV contact discharge per IEC61000-4-2)

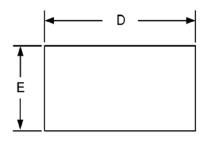
ESD clamping (-8kV contact discharge per IEC61000-4-2)



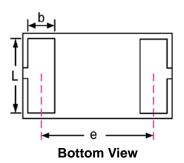
TLP Measurement



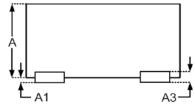
Package outline dimensions



DFN1006-2L



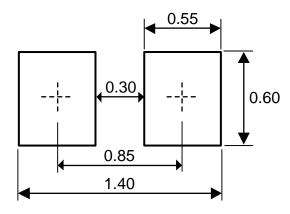
Top View



Side View

Symbol	Dimensions in millimeter			
Symbol	Min.	Тур.	Max.	
А	0.40	-	0.50	
A1	0.00	-	0.05	
A3	0.125 Ref.			
D	0.95	1.00	1.05	
E	0.55	0.60	0.65	
b	0.20	0.25	0.30	
L	0.45	0.50	0.55	
е	0.65 Тур.			

Recommend land pattern (Unit: mm)



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.